



## 3.3V CMOS 12-BIT TO 24-BIT MULTIPLEXED BUS EXCHANGER WITH 3-STATE OUTPUTS AND BUS-HOLD

IDT74ALVCH16271

### FEATURES:

- 0.5 MICRON CMOS Technology
- Typical  $t_{SR(o)}$  (Output Skew) < 250ps
- ESD > 2000V per MIL-STD-883, Method 3015; > 200V using machine model (C = 200pF, R = 0)
- $V_{CC} = 3.3V \pm 0.3V$ , Normal Range
- $V_{CC} = 2.7V$  to  $3.6V$ , Extended Range
- $V_{CC} = 2.5V \pm 0.2V$
- CMOS power levels ( $0.4\mu W$  typ. static)
- Rail-to-Rail output swing for increased noise margin
- Available in SSOP, TSSOP, and TVSOP packages

### DRIVE FEATURES:

- High Output Drivers:  $\pm 24mA$
- Suitable for heavy loads

### APPLICATIONS:

- 3.3V high speed systems
- 3.3V and lower voltage computing systems

### DESCRIPTION:

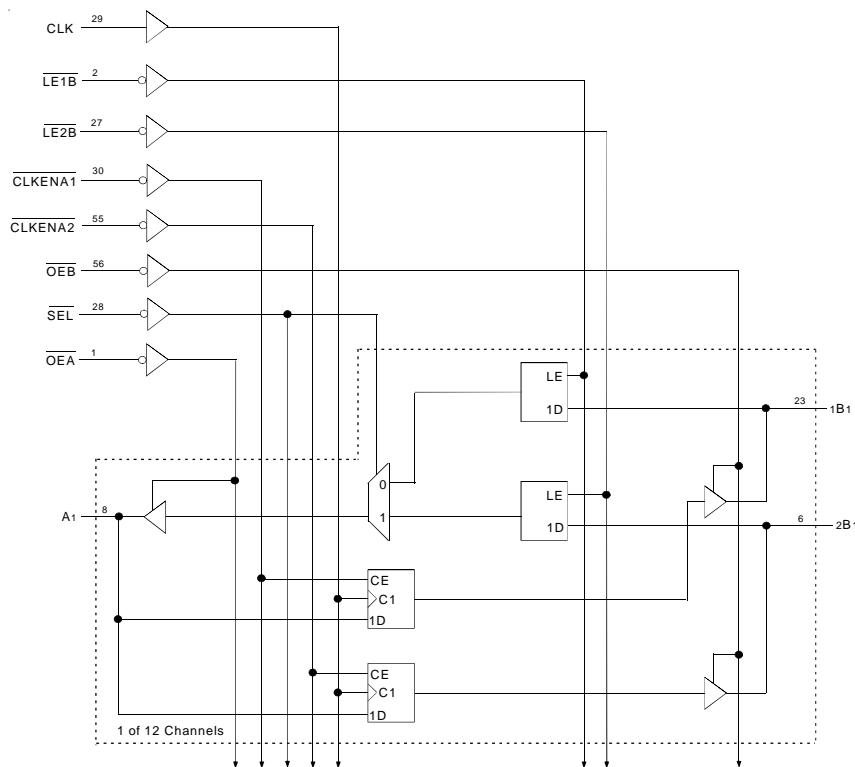
The ALVCH16271 is intended for applications in which two separate data paths must be multiplexed onto, or demultiplexed from, a single data path. This device is particularly suitable as an interface between conventional DRAMs and high-speed microprocessors.

A data is stored in the internal A-to-B registers on the low-to-high transition of the clock (CLK) input, provided that the clock-enable ( $\overline{CLKENA}$ ) inputs are low. Proper control of these inputs allows two sequential 12-bit words to be presented as a 24-bit word on the B port. Transparent latches in the B-to-A path allow asynchronous operation to maximize memory access throughput. These latches transfer data when the latch-enable ( $\overline{LE}$ ) inputs are low. The select ( $\overline{SEL}$ ) line selects 1B or 2B data for the A inputs. Data flow is controlled by the active-low output enables ( $\overline{OEA}$ ,  $\overline{OEB}$ ).

The ALVCH16271 has been designed with a  $\pm 24mA$  output driver. This driver is capable of driving a moderate to heavy load while maintaining speed performance.

The ALVCH16271 has "bus-hold" which retains the inputs' last state whenever the input goes to a high impedance. This prevents floating inputs and eliminates the need for pull-up/down resistors.

### FUNCTIONAL BLOCK DIAGRAM



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INDUSTRIAL TEMPERATURE RANGE

MARCH 1999

## PIN CONFIGURATION

OE <sub>A</sub>	1	56	OE <sub>B</sub>
LE1B	2	55	CLKENA <sub>2</sub>
2B <sub>3</sub>	3	54	2B <sub>4</sub>
GND	4	53	GND
2B <sub>2</sub>	5	52	2B <sub>5</sub>
2B <sub>1</sub>	6	51	2B <sub>6</sub>
Vcc	7	50	Vcc
A <sub>1</sub>	8	49	2B <sub>7</sub>
A <sub>2</sub>	9	48	2B <sub>8</sub>
A <sub>3</sub>	10	47	2B <sub>9</sub>
GND	11	46	GND
A <sub>4</sub>	12	45	2B <sub>10</sub>
A <sub>5</sub>	13	44	2B <sub>11</sub>
A <sub>6</sub>	14	43	2B <sub>12</sub>
A <sub>7</sub>	15	42	1B <sub>12</sub>
A <sub>8</sub>	16	41	1B <sub>11</sub>
A <sub>9</sub>	17	40	1B <sub>10</sub>
GND	18	39	GND
A <sub>10</sub>	19	38	1B <sub>9</sub>
A <sub>11</sub>	20	37	1B <sub>8</sub>
A <sub>12</sub>	21	36	1B <sub>7</sub>
Vcc	22	35	Vcc
1B <sub>1</sub>	23	34	1B <sub>6</sub>
1B <sub>2</sub>	24	33	1B <sub>5</sub>
GND	25	32	GND
1B <sub>3</sub>	26	31	1B <sub>4</sub>
LE2B	27	30	CLKENA <sub>1</sub>
SEL	28	29	CLK

SSOP/ TSSOP/ TVSOP  
TOP VIEWB-TO-A STORAGE ( $\overline{OE_A} = L$ )

Inputs			Outputs		
LE1B	LE2B	$\overline{SEL}$	1Bx	2Bx	A <sub>x</sub>
H	H	X	X	X	A <sub>0</sub> <sup>(2)</sup>
H	H	X	X	X	A <sub>0</sub> <sup>(2)</sup>
L	X	H	L	X	L
L	X	H	H	X	H
X	L	L	X	L	L
X	L	L	X	H	H

ABSOLUTE MAXIMUM RATINGS<sup>(1)</sup>

Symbol	Description	Max	Unit
V <sub>TERM</sub> <sup>(2)</sup>	Terminal Voltage with Respect to GND	-0.5 to +4.6	V
V <sub>TERM</sub> <sup>(3)</sup>	Terminal Voltage with Respect to GND	-0.5 to V <sub>CC</sub> +0.5	V
T <sub>STG</sub>	Storage Temperature	-65 to +150	°C
I <sub>OUT</sub>	DC Output Current	-50 to +50	mA
I <sub>IK</sub>	Continuous Clamp Current, V <sub>I</sub> < 0 or V <sub>I</sub> > V <sub>CC</sub>	±50	mA
I <sub>OK</sub>	Continuous Clamp Current, V <sub>O</sub> < 0	-50	mA
I <sub>CC</sub>	Continuous Current through each V <sub>CC</sub> or GND	±100	mA
I <sub>SS</sub>			

## NOTES:

- Stresses greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.
- V<sub>CC</sub> terminals.
- All terminals except V<sub>CC</sub>.

## CAPACITANCE (TA = +25°C, F = 1.0MHz)

Symbol	Parameter <sup>(1)</sup>	Conditions	Typ.	Max.	Unit
C <sub>IN</sub>	Input Capacitance	V <sub>IN</sub> = 0V	5	7	pF
C <sub>OUT</sub>	Output Capacitance	V <sub>OUT</sub> = 0V	7	9	pF
C <sub>I/O</sub>	I/O Port Capacitance	V <sub>IN</sub> = 0V	7	9	pF

## NOTE:

- As applicable to the device type.

FUNCTION TABLES<sup>(1)</sup>

## OUTPUTENABLE

Inputs		Outputs	
OE <sub>A</sub>	OE <sub>B</sub>	A <sub>x</sub>	1B <sub>x</sub> , 2B <sub>x</sub>
H	H	Z	Z
H	L	Z	Active
L	H	Active	Z
L	L	Active	Active

A-TO-B STORAGE ( $\overline{OE_B} = L$ )

Inputs				Outputs	
CLKENA <sub>1</sub>	CLKENA <sub>2</sub>	CLK	A <sub>x</sub>	1B <sub>x</sub>	2B <sub>x</sub>
H	H	X	X	1B <sub>0</sub> <sup>(2)</sup>	2B <sub>0</sub> <sup>(2)</sup>
L	X	↑	L	L	X
L	X	↑	H	H	X
X	L	↑	L	X	L
X	L	↑	H	X	H

## NOTES:

- H = HIGH Voltage Level  
L = LOW Voltage Level  
X = Don't Care  
Z = High Impedance  
↑ = LOW-to-HIGH transition
- Output level before the indicated steady-state input conditions were established.

## PIN DESCRIPTION

Pin Names	I/O	Description
Ax(1:12)	I/O	Bidirectional Data Port A. Usually connected to the CPU's Address/Data bus. <sup>(1)</sup>
1Bx(1:12)	I/O	Bidirectional Data Port 1B. Usually connected to the even path or even bank of memory. <sup>(1)</sup>
2Bx(1:12)	I/O	Bidirectional Data Port 2B. Usually connected to the odd path or odd bank of memory. <sup>(1)</sup>
CLK	I	Clock Input
CLKENA1	I	Clock Enable Input for the A-1B Register. If CLKENA1 is LOW during the rising edge of CLK, data will be clocked into register A-1B (Active LOW).
CLKENA2	I	Clock Enable Input for the A-2B Register. If CLKENA2 is LOW during the rising edge of CLK, data will be clocked into register A-2B (Active LOW).
LE1B	I	Latch Enable Input for the 1B-A latch
LE2B	I	Latch Enable Input for the 2B-A latch
SEL	I	1B or 2B Port Selection. When HIGH, SEL enables data transfer from 1B Port to A Port. When LOW, SEL enables data transfer from 2B Port to A Port (Active LOW).
OE <sub>A</sub>	I	Output Enable for A Port (Active LOW)
OE <sub>B</sub>	I	Output Enable for B Port (Active LOW)

## NOTE:

1. These pins have "Bus-Hold". All other pins are standard inputs, outputs, or I/Os.

## DC ELECTRICAL CHARACTERISTICS OVER OPERATING RANGE

Following Conditions Apply Unless Otherwise Specified:

Operating Condition: TA = -40°C to +85°C

Symbol	Parameter	Test Conditions		Min.	Typ. <sup>(1)</sup>	Max.	Unit
V <sub>IH</sub>	Input HIGH Voltage Level	V <sub>CC</sub> = 2.3V to 2.7V		1.7	—	—	V
		V <sub>CC</sub> = 2.7V to 3.6V		2	—	—	
V <sub>IL</sub>	Input LOW Voltage Level	V <sub>CC</sub> = 2.3V to 2.7V		—	—	0.7	V
		V <sub>CC</sub> = 2.7V to 3.6V		—	—	0.8	
I <sub>IH</sub>	Input HIGH Current	V <sub>CC</sub> = 3.6V	V <sub>I</sub> = V <sub>CC</sub>	—	—	±5	µA
I <sub>IL</sub>	Input LOW Current	V <sub>CC</sub> = 3.6V	V <sub>I</sub> = GND	—	—	±5	µA
I <sub>OZH</sub>	High Impedance Output Current (3-State Output pins)	V <sub>CC</sub> = 3.6V	V <sub>O</sub> = V <sub>CC</sub>	—	—	±10	µA
			V <sub>O</sub> = GND	—	—	±10	
V <sub>IK</sub>	Clamp Diode Voltage	V <sub>CC</sub> = 2.3V, I <sub>IN</sub> = -18mA		—	-0.7	-1.2	V
V <sub>H</sub>	Input Hysteresis	V <sub>CC</sub> = 3.3V		—	100	—	mV
I <sub>CCL</sub> I <sub>CCH</sub> I <sub>CCZ</sub>	Quiescent Power Supply Current	V <sub>CC</sub> = 3.6V V <sub>IN</sub> = GND or V <sub>CC</sub>		—	0.1	40	µA
ΔI <sub>CC</sub>	Quiescent Power Supply Current Variation	One input at V <sub>CC</sub> - 0.6V, other inputs at V <sub>CC</sub> or GND		—	—	750	µA

## NOTE:

1. Typical values are at V<sub>CC</sub> = 3.3V, +25°C ambient.

## BUS-HOLD CHARACTERISTICS

Symbol	Parameter <sup>(1)</sup>	Test Conditions		Min.	Typ. <sup>(2)</sup>	Max.	Unit
I <sub>BHH</sub>	Bus-Hold Input Sustain Current	V <sub>CC</sub> = 3V	V <sub>I</sub> = 2V	-75	—	—	μA
I <sub>BHL</sub>			V <sub>I</sub> = 0.8V	75	—	—	
I <sub>BHH</sub>	Bus-Hold Input Sustain Current	V <sub>CC</sub> = 2.3V	V <sub>I</sub> = 1.7V	-45	—	—	μA
I <sub>BHL</sub>			V <sub>I</sub> = 0.7V	45	—	—	
I <sub>BHHO</sub>	Bus-Hold Input Overdrive Current	V <sub>CC</sub> = 3.6V	V <sub>I</sub> = 0 to 3.6V	—	—	±500	μA
I <sub>BHLO</sub>							

## NOTES:

1. Pins with Bus-Hold are identified in the pin description.
2. Typical values are at V<sub>CC</sub> = 3.3V, +25°C ambient.

## OUTPUT DRIVE CHARACTERISTICS

Symbol	Parameter	Test Conditions <sup>(1)</sup>		Min.	Max.	Unit
V <sub>OH</sub>	Output HIGH Voltage	V <sub>CC</sub> = 2.3V to 3.6V	I <sub>OH</sub> = -0.1mA	V <sub>CC</sub> - 0.2	—	V
		V <sub>CC</sub> = 2.3V	I <sub>OH</sub> = -6mA	2	—	
		V <sub>CC</sub> = 2.3V	I <sub>OH</sub> = -12mA	1.7	—	
		V <sub>CC</sub> = 2.7V		2.2	—	
		V <sub>CC</sub> = 3V		2.4	—	
		V <sub>CC</sub> = 3V	I <sub>OH</sub> = -24mA	2	—	
V <sub>OL</sub>	Output LOW Voltage	V <sub>CC</sub> = 2.3V to 3.6V	I <sub>OL</sub> = 0.1mA	—	0.2	V
		V <sub>CC</sub> = 2.3V	I <sub>OL</sub> = 6mA	—	0.4	
				—	0.7	
		V <sub>CC</sub> = 2.7V	I <sub>OL</sub> = 12mA	—	0.4	
		V <sub>CC</sub> = 3V	I <sub>OL</sub> = 24mA	—	0.55	

## NOTE:

1. V<sub>H</sub> and V<sub>L</sub> must be within the min. or max. range shown in the DC ELECTRICAL CHARACTERISTICS OVER OPERATING RANGE table for the appropriate V<sub>CC</sub> range. TA = -40°C to +85°C.

## OPERATING CHARACTERISTICS, TA = 25°C

Symbol	Parameter	Test Conditions	V <sub>CC</sub> = 2.5V ± 0.2V	V <sub>CC</sub> = 3.3V ± 0.3V	Unit
			Typical	Typical	
CPD	Power Dissipation Capacitance Ax to xBx, outputs enabled	CL = 0pF, f = 10Mhz	92	105	pF
	Power Dissipation Capacitance Ax to xBx, outputs disabled		61	76	
	Power Dissipation Capacitance xBx to Ax, outputs enabled		39	43	
	Power Dissipation Capacitance xBx to Ax, outputs disabled		11	13	

SWITCHING CHARACTERISTICS<sup>(1)</sup>

Symbol	Parameter	V <sub>CC</sub> = 2.5V ± 0.2V		V <sub>CC</sub> = 2.7V		V <sub>CC</sub> = 3.3V ± 0.3V		Unit
		Min.	Max.	Min.	Max.	Min.	Max.	
f <sub>MAX</sub>		130	—	130	—	130	—	MHz
t <sub>PLH</sub>	Propagation Delay CLK to xBx	1	6.2	—	5	1	4.3	ns
t <sub>PLH</sub>	Propagation Delay xBx to Ax	1	5.3	—	4.7	1.4	4	ns
t <sub>PLH</sub>	Propagation Delay L <sub>E</sub> to Ax	1	6	—	5.9	1.4	4.8	ns
t <sub>PLH</sub>	Propagation Delay S <sub>EL</sub> to Ax	1.1	6.4	—	6.2	1.3	5.2	ns
t <sub>PZH</sub>	Output Enable Time O <sub>EB</sub> to Ax or O <sub>EB</sub> to xBx	1	6	—	6.1	1	5.1	ns
t <sub>PLZ</sub>	Output Disable Time O <sub>EB</sub> to Ax or O <sub>EB</sub> to xBx	1.4	5.4	—	4.6	1.7	4.2	ns
t <sub>SU</sub>	Set-up Time, Ax data before CLK↑	2.6	—	2.1	—	1.7	—	ns
t <sub>SU</sub>	Set-up Time, Bx data before L <sub>E</sub>	1.7	—	1.5	—	1.3	—	ns
t <sub>SU</sub>	Set-up Time, C <sub>LKEN</sub> before CLK↑	1.6	—	1.3	—	1	—	ns
t <sub>H</sub>	Hold Time, Ax data after CLK↑	0.6	—	0.6	—	0.7	—	ns
t <sub>H</sub>	Hold Time, Bx data after L <sub>E</sub>	0.9	—	0.9	—	1.1	—	ns
t <sub>H</sub>	Hold Time, C <sub>LKEN</sub> after CLK↑	1	—	0.9	—	0.9	—	ns
t <sub>W</sub>	Pulse Width, CLK HIGH or LOW	3.3	—	3.3	—	3.3	—	ns
t <sub>W</sub>	Pulse Width, L <sub>E</sub> x <sub>B</sub> LOW	3.3	—	3.3	—	3.3	—	ns
t <sub>SK(O)</sub>	Output Skew <sup>(2)</sup>	—	—	—	—	—	500	ps

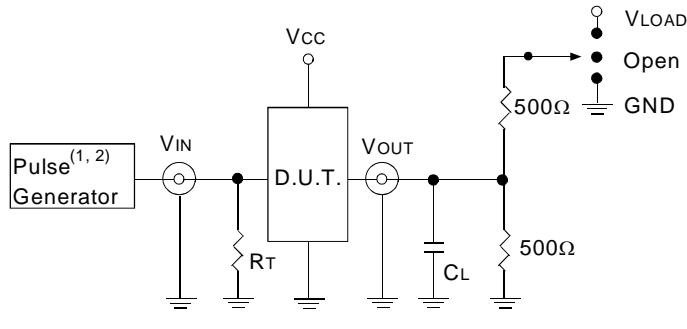
## NOTES:

- See TEST CIRCUITS AND WAVEFORMS. T<sub>A</sub> = -40°C to +85°C.
- Skew between any two outputs of the same package and switching in the same direction.

## TEST CIRCUITS AND WAVEFORMS

## TEST CONDITIONS

Symbol	$V_{CC}^{(1)} = 3.3V \pm 0.3V$	$V_{CC}^{(1)} = 2.7V$	$V_{CC}^{(2)} = 2.5V \pm 0.2V$	Unit
$V_{LOAD}$	6	6	$2 \times V_{CC}$	V
$V_{IH}$	2.7	2.7	$V_{CC}$	V
$V_T$	1.5	1.5	$V_{CC} / 2$	V
$V_{LZ}$	300	300	150	mV
$V_{HZ}$	300	300	150	mV
$C_L$	50	50	30	pF



Test Circuit for All Outputs

## DEFINITIONS:

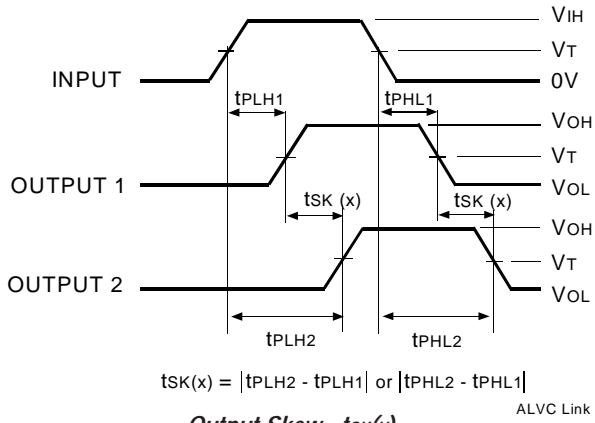
 $C_L$  = Load capacitance: includes jig and probe capacitance. $R_T$  = Termination resistance: should be equal to  $Z_{OUT}$  of the Pulse Generator.

## NOTES:

1. Pulse Generator for All Pulses: Rate  $\leq 1.0\text{MHz}$ ;  $t_f \leq 2.5\text{ns}$ ;  $t_r \leq 2.5\text{ns}$ .
2. Pulse Generator for All Pulses: Rate  $\leq 1.0\text{MHz}$ ;  $t_f \leq 2\text{ns}$ ;  $t_r \leq 2\text{ns}$ .

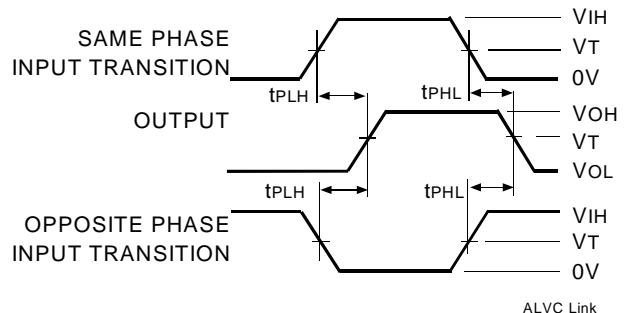
## SWITCH POSITION

Test	Switch
Open Drain	
Disable Low	$V_{LOAD}$
Enable Low	
Disable High	$GND$
All Other Tests	Open

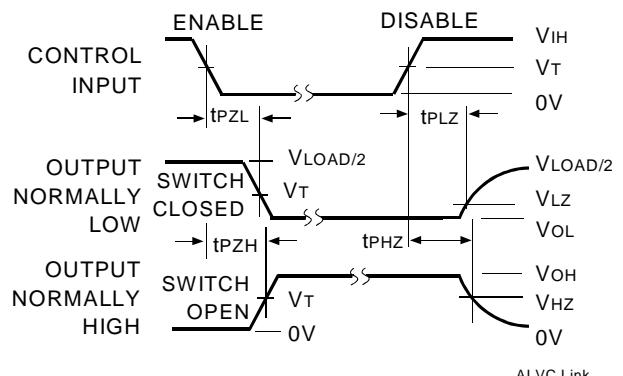
Output Skew -  $t_{SK(x)}$ 

## NOTES:

1. For  $t_{SK(o)}$  OUTPUT1 and OUTPUT2 are any two outputs.
2. For  $t_{SK(b)}$  OUTPUT1 and OUTPUT2 are in the same bank.



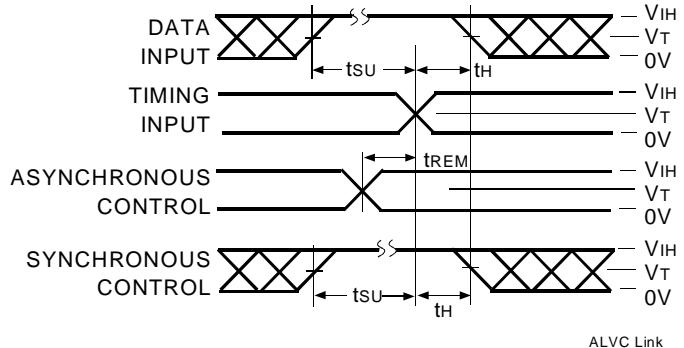
Propagation Delay



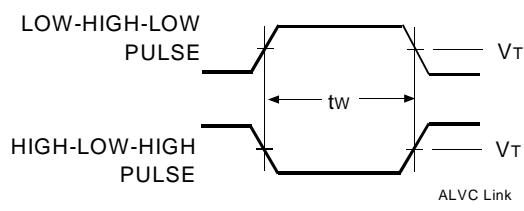
Enable and Disable Times

## NOTE:

1. Diagram shown for input Control Enable-LOW and input Control Disable-HIGH.



Set-up, Hold, and Release Times



Pulse Width

## ORDERING INFORMATION

IDT	XX	ALVC	X	XX	XXX	XX	
Temp. Range		Bus-Hold		Family	Device Type	Package	
						PV	Shrink Small Outline Package
						PA	Thin Shrink Small Outline Package
						PF	Thin Very Small Outline Package
					271	12-Bit to 24-Bit Multiplexed Bus Exchanger with 3-State Outputs	
					16	Double-Density, ±24mA	
					H	Bus-Hold	
					74	–40°C to +85°C	



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